

# MJE700G, MJE702G, MJE703G (PNP), MJE800G, MJE802G, MJE803G (NPN)



ON Semiconductor®

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## Plastic Darlington Complementary Silicon Power Transistors

These devices are designed for general-purpose amplifier and low-speed switching applications.

### Features

- High DC Current Gain –  $h_{FE} = 2000$  (Typ) @  $I_C = 2.0$  Adc
- Monolithic Construction with Built-in Base-Emitter Resistors to Limit Leakage – Multiplication
- Choice of Packages – MJE700 and MJE800 Series
- These Devices are Pb-Free and are RoHS Compliant\*

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage MJE700G, MJE800G MJE702G, MJE703G, MJE802G, MJE803G	$V_{CEO}$	60 80	Vdc
Collector-Base Voltage MJE700G, MJE800G MJE702G, MJE703G, MJE802G, MJE803G	$V_{CB}$	60 80	Vdc
Emitter-Base Voltage	$V_{EB}$	5.0	Vdc
Collector Current	$I_C$	4.0	Adc
Base Current	$I_B$	0.1	Adc
Total Power Dissipation @ $T_C = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	40 0.32	W mW/°C
Operating and Storage Junction Temperature Range	$T_J, T_{stg}$	-55 to +150	°C

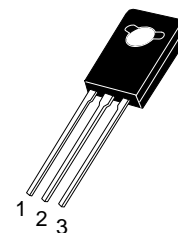
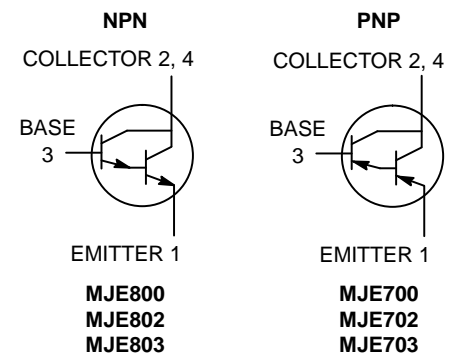
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	3.12	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	83.3	°C/W

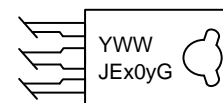
\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## 4.0 AMPERE DARLINGTON POWER TRANSISTORS COMPLEMENTARY SILICON 40 WATT



TO-225  
CASE 77-09  
STYLE 1

### MARKING DIAGRAM



Y = Year  
WW = Work Week  
JEx0y = Device Code  
x = 7 or 8  
y = 0, 2, or 3  
G = Pb-Free Package

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

# MJE700G, MJE702G, MJE703G (PNP), MJE800G, MJE802G, MJE803G (NPN)

## ELECTRICAL CHARACTERISTICS (T<sub>C</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
<b>OFF CHARACTERISTICS</b>				
Collector–Emitter Breakdown Voltage (Note 1) (I <sub>C</sub> = 50 mAdc, I <sub>B</sub> = 0) MJE700G, MJE800G MJE702G, MJE703G, MJE802G, MJE803G	V <sub>(BR)CEO</sub>	60 80	– –	Vdc
Collector Cutoff Current (V <sub>CE</sub> = 60 Vdc, I <sub>B</sub> = 0) MJE700G, MJE800G (V <sub>CE</sub> = 80 Vdc, I <sub>B</sub> = 0) MJE702G, MJE703G, MJE802G, MJE803G	I <sub>CEO</sub>	– –	100 100	μAdc
Collector Cutoff Current (V <sub>CB</sub> = Rated BV <sub>CEO</sub> , I <sub>E</sub> = 0) (V <sub>CB</sub> = Rated BV <sub>CEO</sub> , I <sub>E</sub> = 0, T <sub>C</sub> = 100°C)	I <sub>CBO</sub>	– –	100 500	μAdc
Emitter Cutoff Current (V <sub>BE</sub> = 5.0 Vdc, I <sub>C</sub> = 0)	I <sub>EBO</sub>	–	2.0	mAdc

## ON CHARACTERISTICS

DC Current Gain (Note 1) (I <sub>C</sub> = 1.5 Adc, V <sub>CE</sub> = 3.0 Vdc) MJE700G, MJE702G, MJE800G, MJE802G (I <sub>C</sub> = 2.0 Adc, V <sub>CE</sub> = 3.0 Vdc) MJE703G, MJE803G (I <sub>C</sub> = 4.0 Adc, V <sub>CE</sub> = 3.0 Vdc) All devices	h <sub>FE</sub>	750 750 100	– – –	–
Collector–Emitter Saturation Voltage (Note 1) (I <sub>C</sub> = 1.5 Adc, I <sub>B</sub> = 30 mAdc) MJE700G, MJE702G, MJE800G, MJE802G (I <sub>C</sub> = 2.0 Adc, I <sub>B</sub> = 40 mAdc) MJE703G, MJE803G (I <sub>C</sub> = 4.0 Adc, I <sub>B</sub> = 40 mAdc) All devices	V <sub>CE(sat)</sub>	– – –	2.5 2.8 3.0	Vdc
Base–Emitter On Voltage (Note 1) (I <sub>C</sub> = 1.5 Adc, V <sub>CE</sub> = 3.0 Vdc) MJE700G, MJE702G, MJE800G, MJE802G (I <sub>C</sub> = 2.0 Adc, V <sub>CE</sub> = 3.0 Vdc) MJE703G, MJE803G (I <sub>C</sub> = 4.0 Adc, V <sub>CE</sub> = 3.0 Vdc) All devices	V <sub>BE(on)</sub>	– – –	2.5 2.5 3.0	Vdc

## DYNAMIC CHARACTERISTICS

Small–Signal Current Gain (I <sub>C</sub> = 1.5 Adc, V <sub>CE</sub> = 3.0 Vdc, f = 1.0 MHz)	h <sub>fe</sub>	1.0	–	–
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Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

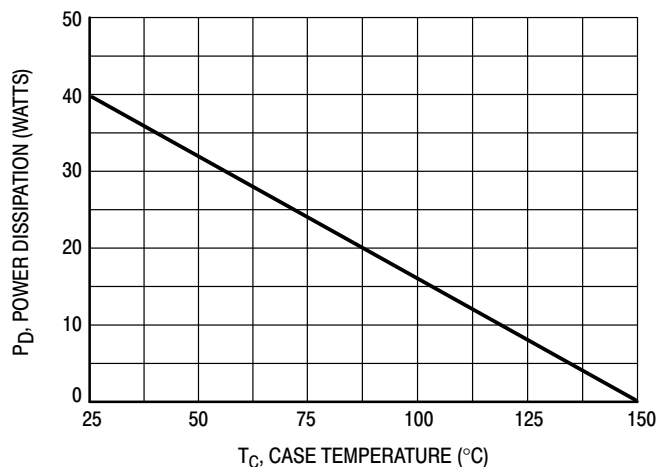


Figure 1. Power Derating

# MJE700G, MJE702G, MJE703G (PNP), MJE800G, MJE802G, MJE803G (NPN)

$R_B$  &  $R_C$  VARIED TO OBTAIN DESIRED CURRENT LEVELS  
 $D_1$ , MUST BE FAST RECOVERY TYPE, e.g.:  
 1N5825 USED ABOVE  $I_B \approx 100$  mA  
 MSD6100 USED BELOW  $I_B \approx 100$  mA

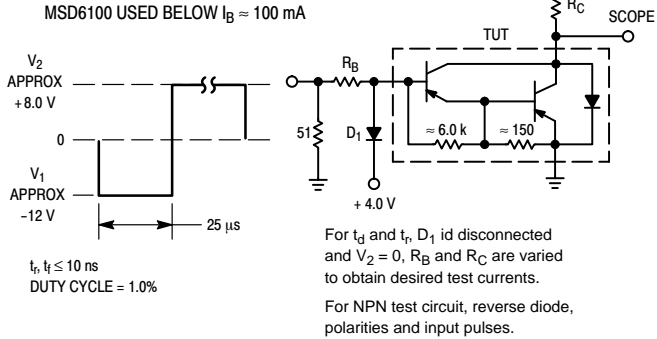


Figure 2. Switching Times Test Circuit

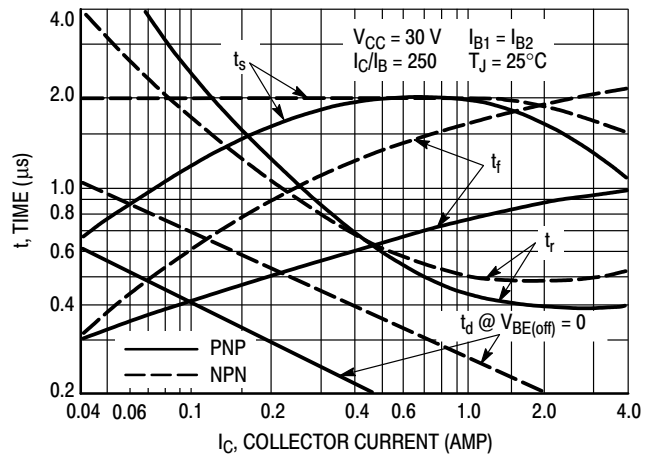


Figure 3. Switching Times

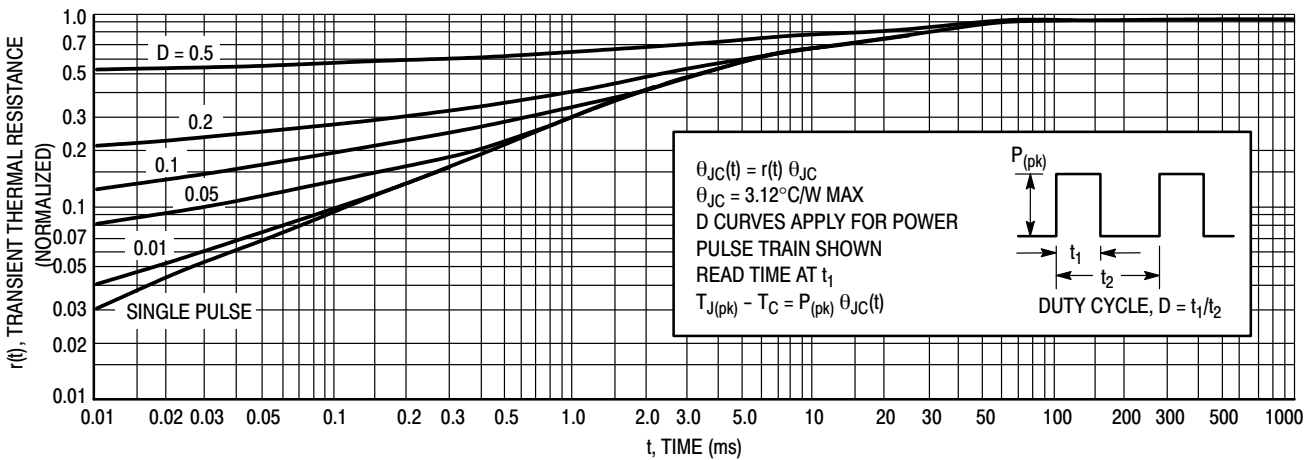


Figure 4. Thermal Response (MJE700, 800 Series)

## ACTIVE-REGION SAFE-OPERATING AREA

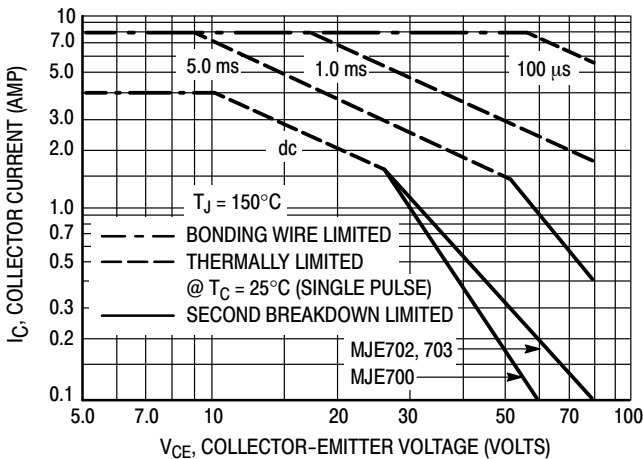


Figure 5. MJE700 Series

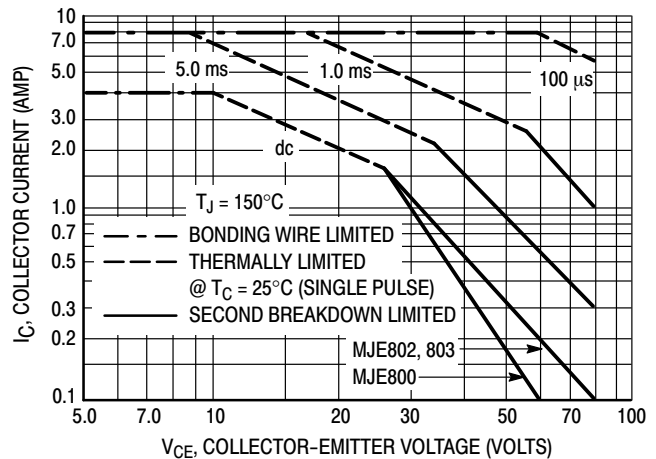


Figure 6. MJE800 Series

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate  $I_C - V_{CE}$  limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figures 5 and 6 are based on  $T_{J(pk)} = 150^\circ\text{C}$ ;  $T_C$  is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided  $T_{J(pk)} < 150^\circ\text{C}$ .  $T_{J(pk)}$  may be calculated from the data in Figure 4. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

MJE700G, MJE702G, MJE703G (PNP), MJE800G, MJE802G, MJE803G (NPN)

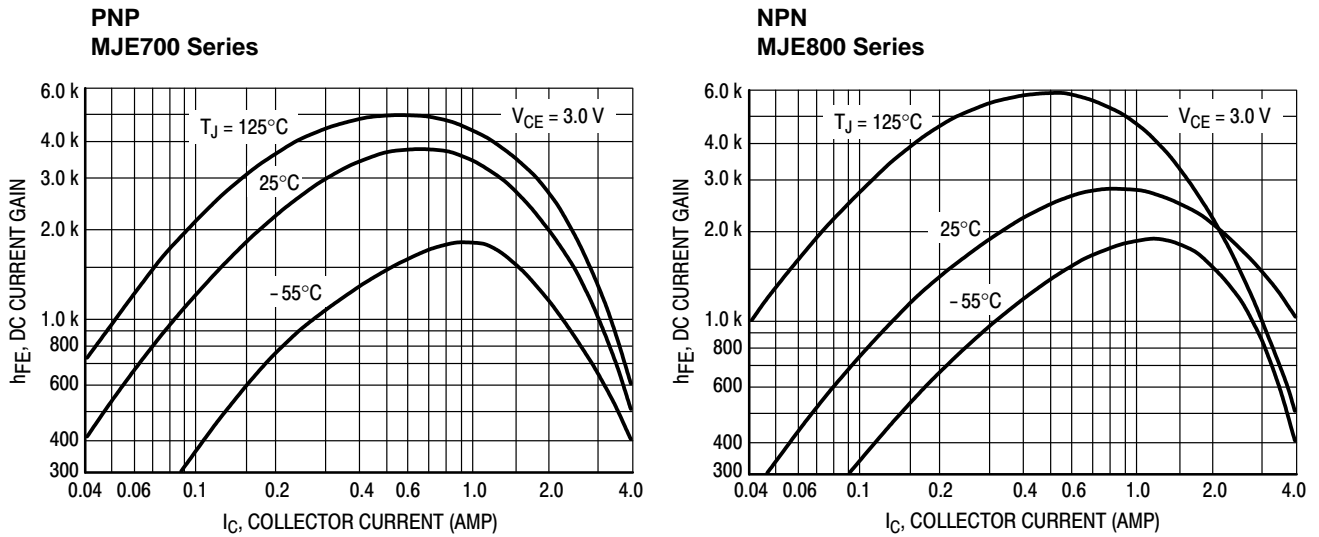


Figure 7. DC Current Gain

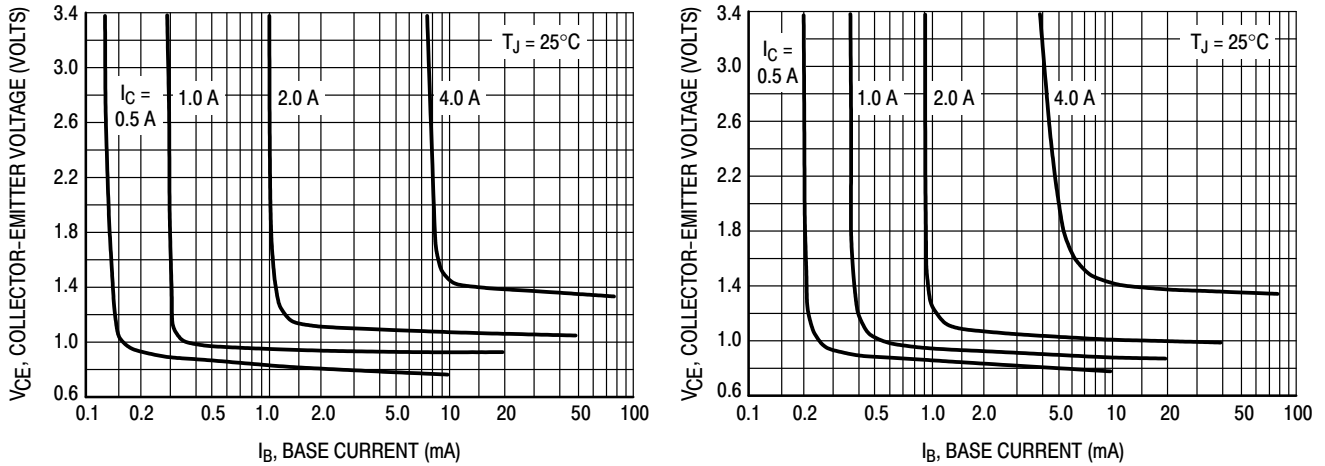


Figure 8. Collector Saturation Region

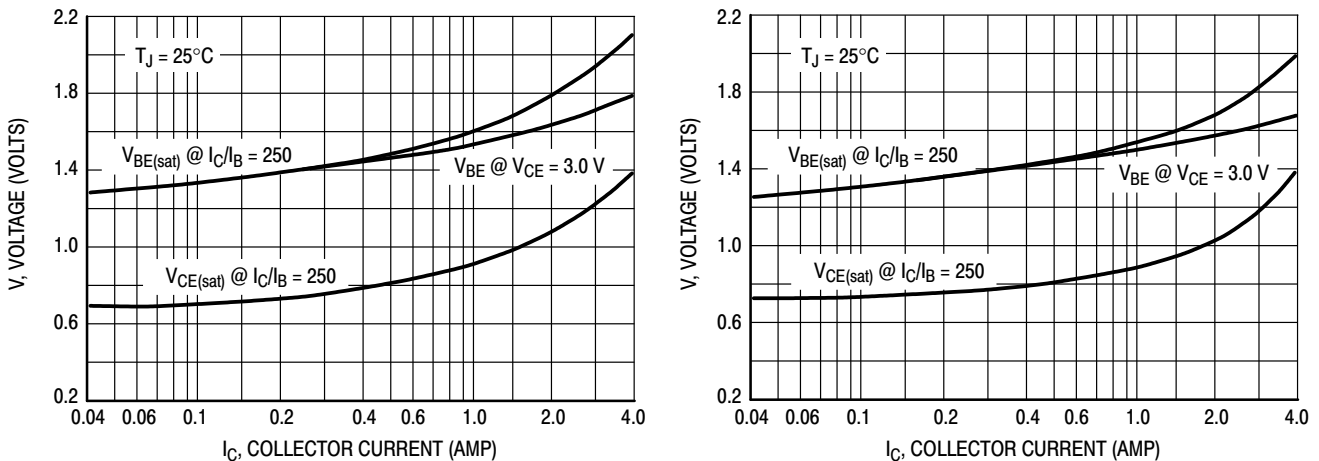


Figure 9. "On" Voltages

# MJE700G, MJE702G, MJE703G (PNP), MJE800G, MJE802G, MJE803G (NPN)

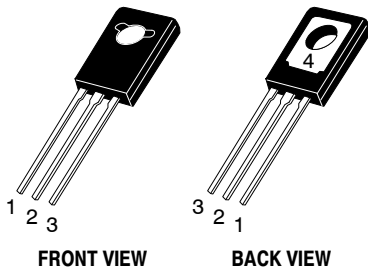
## ORDERING INFORMATION

Device	Package	Shipping
MJE700G	TO-225 (Pb-Free)	50 Units / Bulk
MJE702G	TO-225 (Pb-Free)	50 Units / Bulk
MJE703G	TO-225 (Pb-Free)	50 Units / Bulk
MJE800G	TO-225 (Pb-Free)	50 Units / Bulk
MJE802G	TO-225 (Pb-Free)	50 Units / Bulk
MJE803G	TO-225 (Pb-Free)	50 Units / Bulk

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

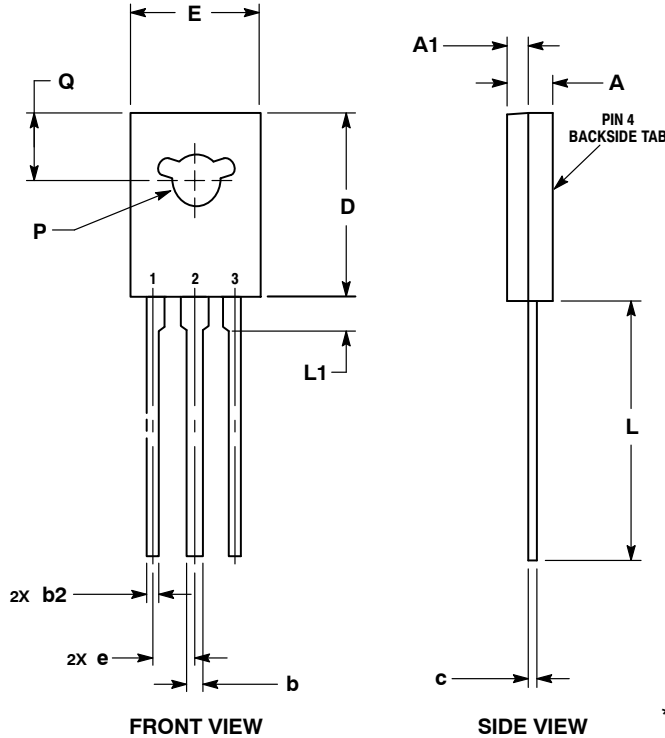
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TO-225  
CASE 77-09  
ISSUE AD

DATE 25 MAR 2015

SCALE 1:1

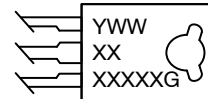


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. NUMBER AND SHAPE OF LUGS OPTIONAL.

DIM	MILLIMETERS	
	MIN	MAX
A	2.40	3.00
A1	1.00	1.50
b	0.60	0.90
b2	0.51	0.88
c	0.39	0.63
D	10.60	11.10
E	7.40	7.80
e	2.04	2.54
L	14.50	16.63
L1	1.27	2.54
P	2.90	3.30
Q	3.80	4.20

GENERIC MARKING DIAGRAM\*



- Y = Year
- WW = Work Week
- XXXXX = Device Code
- G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "µ", may or may not be present.

- |   |   |   |   |   |
|---|---|---|---|---|
| <p>STYLE 1:<br/>PIN 1. EMITTER<br/>2., 4. COLLECTOR<br/>3. BASE</p> | <p>STYLE 2:<br/>PIN 1. CATHODE<br/>2., 4. ANODE<br/>3. GATE</p> | <p>STYLE 3:<br/>PIN 1. BASE<br/>2., 4. COLLECTOR<br/>3. EMITTER</p> | <p>STYLE 4:<br/>PIN 1. ANODE 1<br/>2., 4. ANODE 2<br/>3. GATE</p> | <p>STYLE 5:<br/>PIN 1. MT 1<br/>2., 4. MT 2<br/>3. GATE</p>     |
| <p>STYLE 6:<br/>PIN 1. CATHODE<br/>2., 4. GATE<br/>3. ANODE</p>     | <p>STYLE 7:<br/>PIN 1. MT 1<br/>2., 4. GATE<br/>3. MT 2</p>     | <p>STYLE 8:<br/>PIN 1. SOURCE<br/>2., 4. GATE<br/>3. DRAIN</p>      | <p>STYLE 9:<br/>PIN 1. GATE<br/>2., 4. DRAIN<br/>3. SOURCE</p>    | <p>STYLE 10:<br/>PIN 1. SOURCE<br/>2., 4. DRAIN<br/>3. GATE</p> |

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DESCRIPTION:	TO-225	PAGE 1 OF 1

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